03090

For:

Fransmitted herewith for filing is the Patent Application of:

mou-shiung lin, michael chen, chien kang chou, mark chou



22782 U.S. PTC 10/796427

POST-PASSIVATION METAL SCHEME ON AN IC CHIP WITH COPPER INTERCONNECTION

Enclosed are:						
X 5 sheets of drawing(s) - formal.						
X An as	An assignment of the invention to Megic Corporation					
An as	An associate power of attorney X Applicant claims small entity status					
Request & Certification under 35 USC 122(b)(2)(b)(i)						
The filing fee ha	s been calculated as shown	n below:				
	(Col. 1)	(Col. 2)		SMALL ENTITY		
FOR:	NO. FILED	NO. EXTRA	RATE	FEE		
BASIC FEE				\$ 385.		
TOTAL CLAI	MS <b>68</b> -20=	48	x 9=	\$ 432.		
INDEP CLAII	4S 12 -3=		x 43 =	\$ 387.		
			SUB TOTAL	\$ 1,204.		
			ASSIGNMENT	\$40.		
			TOTAL .	\$ 1,244.		
X Please charge my Deposit Account No. 19-0033 in the amount of \$ 1,244. A duplicate copy of this sheet is enclosed.						
The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any						
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X Any additional filing fees required under 37 CFR §1.16.						
X Any patent application processing fees under 37 CFR §1.17.						
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## **EXPRESS MAIL CERTIFICATE**

STEPHEN'B. ACKERMAN, REG. NO. 37,761

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I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, Applicant and or Attorney requests the date of deposit as the Filing Date.

Signature /